



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSZ12DN20NS3 G	Issued	24. February 2022
MA#	MA005709191		
Package	PG-TSDSON-8-38	Weight*	35.89 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.676	1.88	1.88	18844	18844
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		99	
	non noble metal	zinc	7440-66-6	0.014	0.04		395	
	non noble metal	iron	7439-89-6	0.283	0.79		7894	
	non noble metal	copper	7440-50-8	11.505	32.05	32.89	320545	328933
wire	noble metal	gold	7440-57-5	0.036	0.10	0.10	1014	1014
encapsulation	organic material	carbon black	1333-86-4	0.038	0.10		1048	
	plastics	epoxy resin	-	1.938	5.40		53983	
	inorganic material	silicondioxide	60676-86-0	16.836	46.92	52.42	469077	524108
leadfinish	non noble metal	tin	7440-31-5	0.370	1.03	1.03	10311	10311
plating	noble metal	silver	7440-22-4	0.081	0.23	0.23	2251	2251
solder	non noble metal	tin	7440-31-5	0.017	0.05		471	
	noble metal	silver	7440-22-4	0.021	0.06		589	
	non noble metal	lead	7439-92-1	0.808	2.25	2.36	22510	23570
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001			27	
	non noble metal	zinc	7440-66-6	0.004	0.01		109	
	non noble metal	iron	7439-89-6	0.078	0.22		2183	
	non noble metal	copper	7440-50-8	3.182	8.86	9.09	88650	90969
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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